

ABSTRACT OF THE DISCLOSURE

In a semiconductor device, each of the leads is provided with guided-surfaces that are inclined surfaces and each of the bumps is provided with a recess that has guide-surfaces formed by inclined surfaces. The leads are smoothly guided toward the centers of the upper surfaces of the bumps with the aides of the inclined surfaces formed on the leads and bumps, so that the attitude of the leads is corrected and the leads are snugly brought into the recess and prevented from falling off of the bump.

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